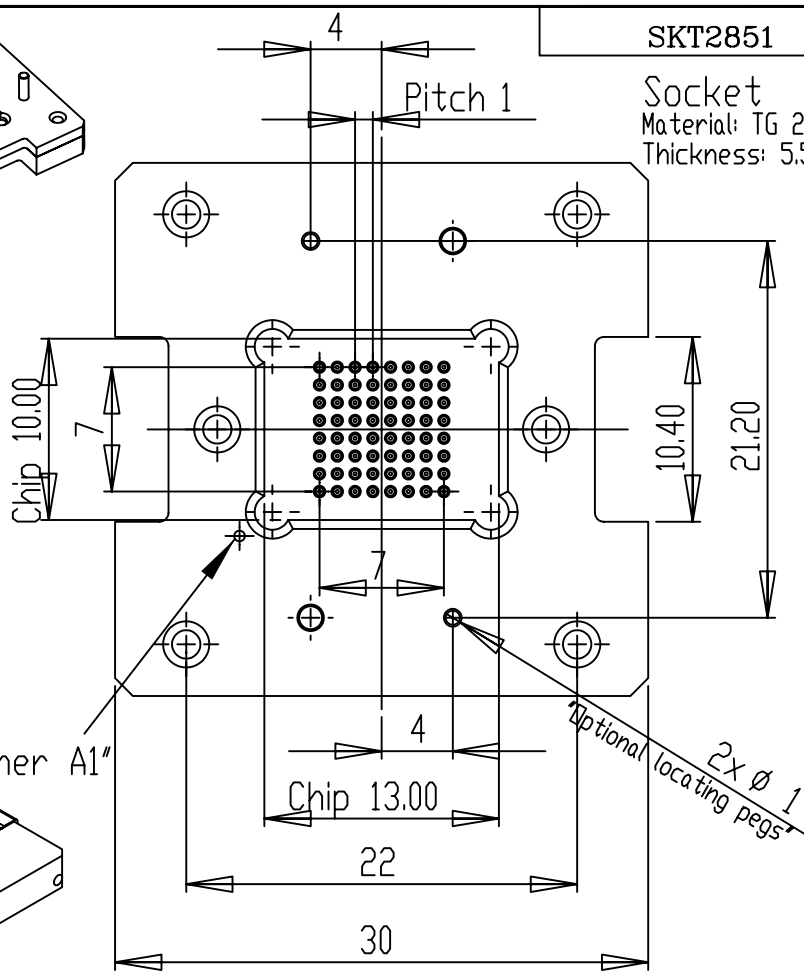
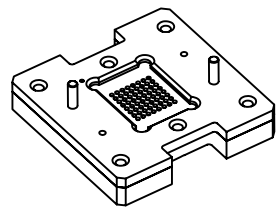
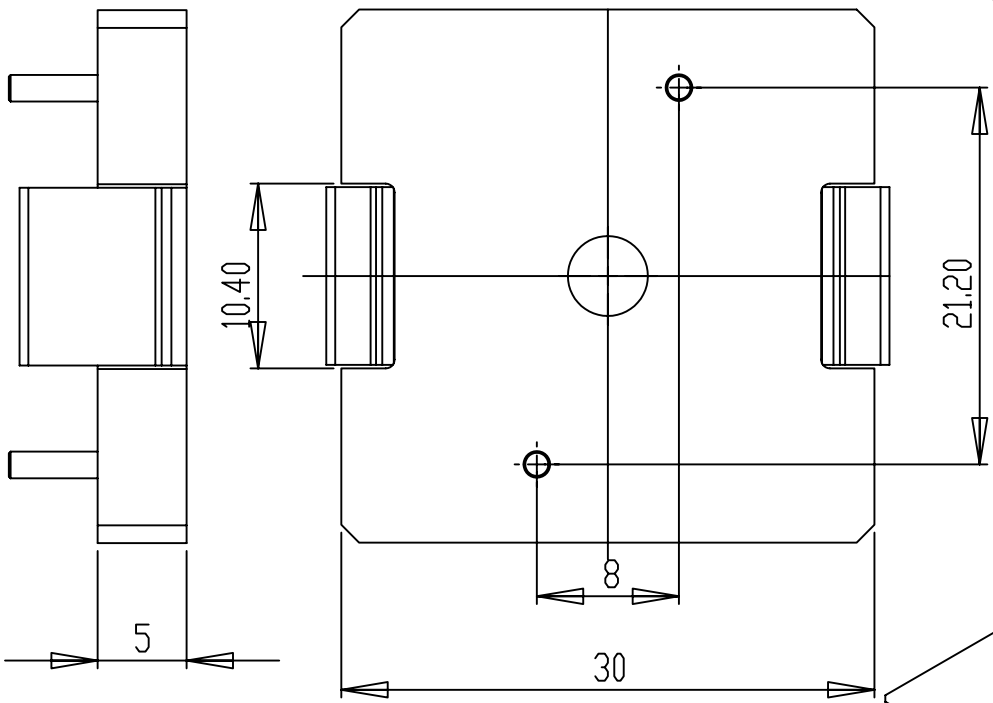


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	01/18/07	H.N.

Retention frame
Material: Epoxy FR4

SKT2851

Socket
Material: TG 200
Thickness: 5.50mm



"Lid pressure adjustment is pre-set at the factory. Tampering with the setting may damage the socket and/or device and will invalidate your warranty."

PACKAGE SPECIFICATIONS

PIN COUNT	= 64
LEAD PITCH	= 1.00mm
GRID SIZE	= 8X8
PACKAGE SIZE	= 10.00X13.00mm
IC BALL DIA	= 0.70mm MAX
BALL HEIGHT	= 0.50mm MAX.

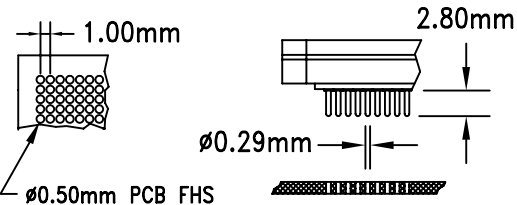
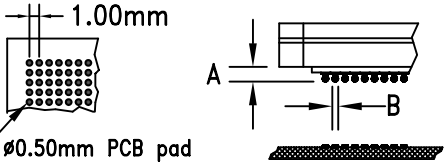
PCB holes for locating pegs
- ø1.10±0.02
Note: Locating pegs can also be soldered to PCB if plated-thru holes are provided

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED

RECOMMENDED PAD LAYOUT

SURFACE MOUNT STYLE		
REGULAR SMT STYLE XX = SM YY = 30	RAISED SMT STYLE XX = SR YY = 29	SPECIAL RAISED SMT STYLE XX = SC YY = 28

SOLDERTAIL = THRU HOLE STYLE
XX = ET
YY = 70



28= Special raised SMT: A = 4.50mm; B= 0.37mm
29= raised SMT: A = 3.20mm; B= 0.37mm
30= standard SMT: A = 0.80mm; B= 0.37mm



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— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
TEL:(408)982-0660 FAX:(408)982-0664

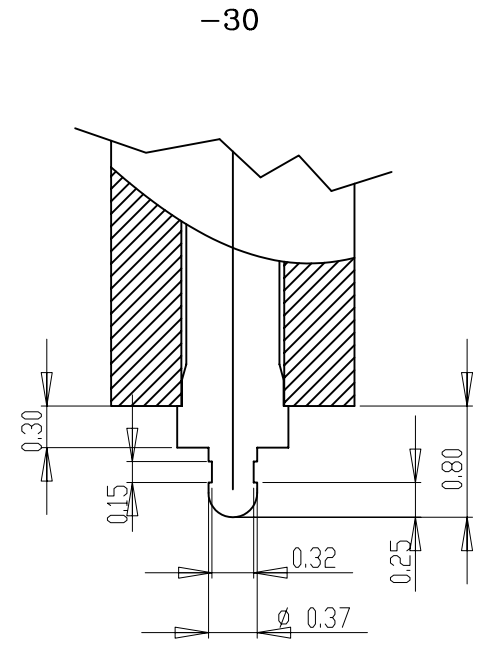
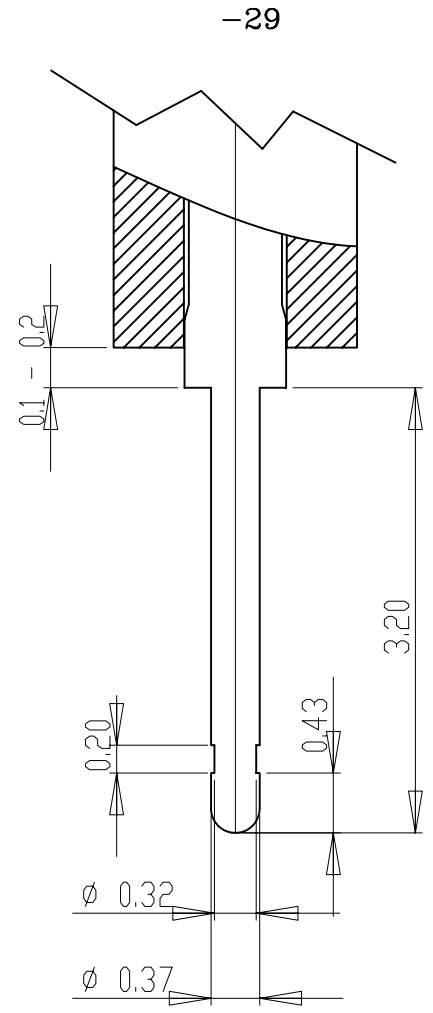
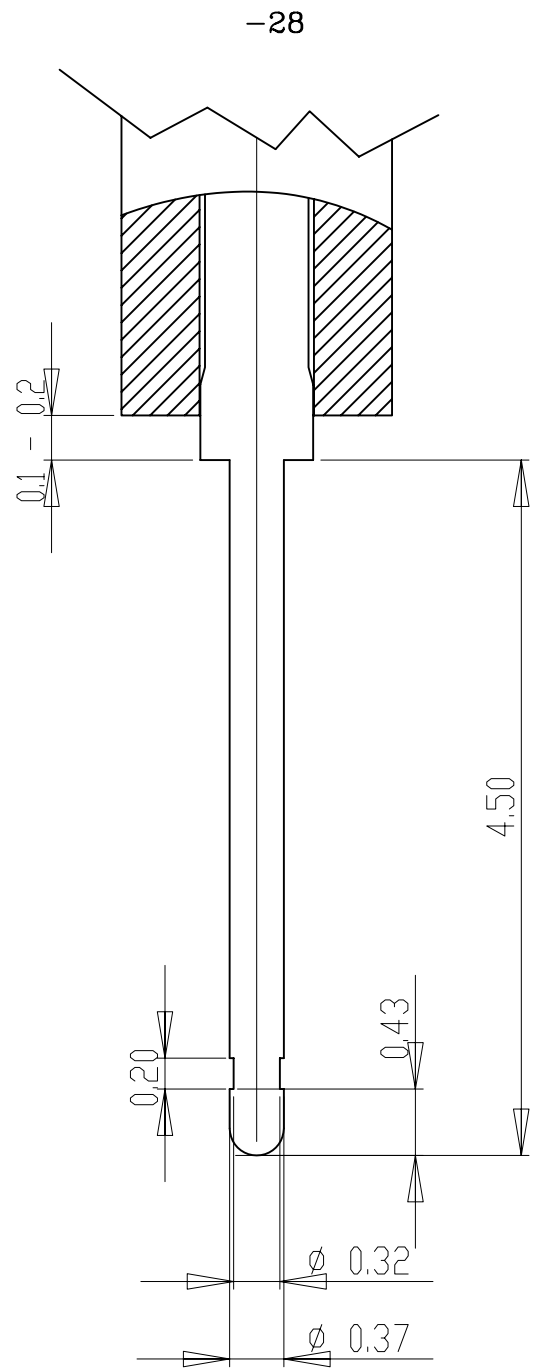
GENERAL TOLERANCES: ±0.10

SHEET: 1 OF 1	DATE: 01/18/07	REVISION: A	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.	ITEM: S-MUQ-08-064-XX	
Scale N/A DO NOT SCALE DRAWING			DESCRIPTION: BUQ-064-3BG008-YY

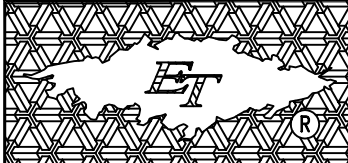
All Dimensions Are Nominal For A 1.00mm Pitch BGA Package

REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	06/28/06	H.N.

ET-1.00mm



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SHEET: 1 OF 1	DATE: 06/28/06	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: 1.00mm PITCH PIN	DESCRIPTION: 1.00mm PITCH PIN
Scale N/A	DO NOT SCALE DRAWING		